

# TKL8255

## Processor Board

RUGGEDIZED | MADE IN USA

## Swift Performance with Xeon® or Core™

The TKL8255 rugged processor board is designed to tackle the widest range of industrial and embedded computing challenges using a powerful Intel Xeon or Core processor in a 2U, 3U, 4U or 5U rugged chassis. It's what your application deserves.



### NVMe Drive Support

The TKL8255 is capable of utilizing those ultra-fast NVMe M.2 drives for when you need a PCIe-based storage solution.

### 20 Lanes of PCIe Gen 3

Not 5, not 10, not 15, but 20 lanes of PCIe Gen 3 ensures significant expandability when paired with a PICMG 1.3 Series Backplane.

### ECC Memory Support

Stop data corruption dead in its tracks with error-correcting code memory, perfect for mission-critical applications.

## Section 5 / System Overview

### PROCESSOR BOARD

TKL8255 | Type: PICMG 1.3 Series

### COMPATIBLE CHASSIS MODEL NUMBER(S)

TRC2010, THS2085, TRC2019, THS4086, THS4095, TRS4019, TRC3010

[Contact us for custom options](#)

### PROCESSORS

- ▶ Intel® Core™ or Xeon® E processors; LGA1151 Socket
- ▶ CPU TDP support up to 125W

CPU	Cores/Threads	Frequency	Cache	TDP
i5-7500	4/4	3.40-3.80GHZ	6 MB	65W
i7-7700	4/8	3.60-4.20GHZ	8 MB	65W
E3-1275v6	4/8	3.80-4.20GHZ	8 MB	73W

### MEMORY

**Slots:** 4x DDR4 DIMM sockets

**Dual:** Channel memory support

**Capacity:** Up to 64GB DDR4 ECC DIMM total RAM

**Type:** ECC DDR4-2400 UDIMM

**DIMM Sizes:** 16GB, 8GB, or 4GB

**Error Detection:** Corrects single-bit errors and detects double-bit errors using ECC memory

\*ECC support dependent on CPU installed

### STORAGE

**Type(s):**

- ▶ 6x SSD/HDD SATA3 (6 Gbps) drives of any size
- ▶ 1x M.2 NVMe x4 PCIe 3.0 lanes
  - 2242,2260, & 2280 card M.2 lengths

**Capacity:** Up to 12TB per drive (larger capacities available upon request)

**SATA Modes:** AHCI or RAID

**RAID:** Intel® RSTe SATA RAID support 0/1/5/10 Modes

### ON-BOARD DEVICES

**Chipset:** Intel® C236

**Network Controllers:**

- ▶ Dual Intel® i350 Gigabit Ethernet
- ▶ Intel® i219 Gigabit Ethernet

**Graphics:** Intel® Integrated Graphics

**TPM 2.0:** Secure cryptoprocessor that helps you with actions such as generating, storing, and limiting the use of cryptographic keys. A requirement for Microsoft's bitlocker drive volume encryption features.

### INPUT / OUTPUT

**USB:** 12x USB 3.0/2.0 ports

- ▶ 2x USB 3.0 ports on rear I/O
- ▶ 2x USB 3.0 ports via PCB internal header
- ▶ 4x USB 2.0 ports via PCB internal headers
- ▶ 4x USB 2.0 ports via PICMG connection to Backplane

**Display:** 1x DisplayPort

**DVI-D:** 2x DVI-D internal ports

**LAN:** 3x RJ-45 Gigabit Ethernet LAN ports

- ▶ 2x RJ-45 Gigabit Ethernet LAN ports on rear I/O
- ▶ 1x RJ-45 Gigabit Ethernet LAN port via PICMG to Backplane

**Serial:** 2x RS232, R422, R485 DB9 Serial headers

**PCI:** 2.2 Compliant via PCIe to PCI bridge at 32bit/33MHz

**LPC Bus:** For TPM, Super I/O, and Serial support

### PROCESSOR BOARD DIMENSIONS

Length: 13.345" | 30.858 cm

Width: 5.570" | 14.6 cm

\*System dimensions dependent on rugged chassis selection

### SYSTEM BIOS

**BIOS Type:** 128Mb Macronix MX25L12835FM2I-10G SPI

Serial EEPROM (SPI Flash)

**BIOS Features:**

- ▶ Plug and Play (PnP)
- ▶ APM 1.2
- ▶ PCI 2.2
- ▶ ACPI 1.0 / 2.0
- ▶ USB Keyboard Support
- ▶ SMBIOS 2.3
- ▶ UEFI

### ENVIRONMENTAL SPECIFICATIONS

Operating Temperature: 0°C - 50°C

Storage Temperature: -40°C - 70°C

Operating Humidity: 8% - 90% Non-Condensing

Non-operating Humidity: 5% - 95% Non-Condensing

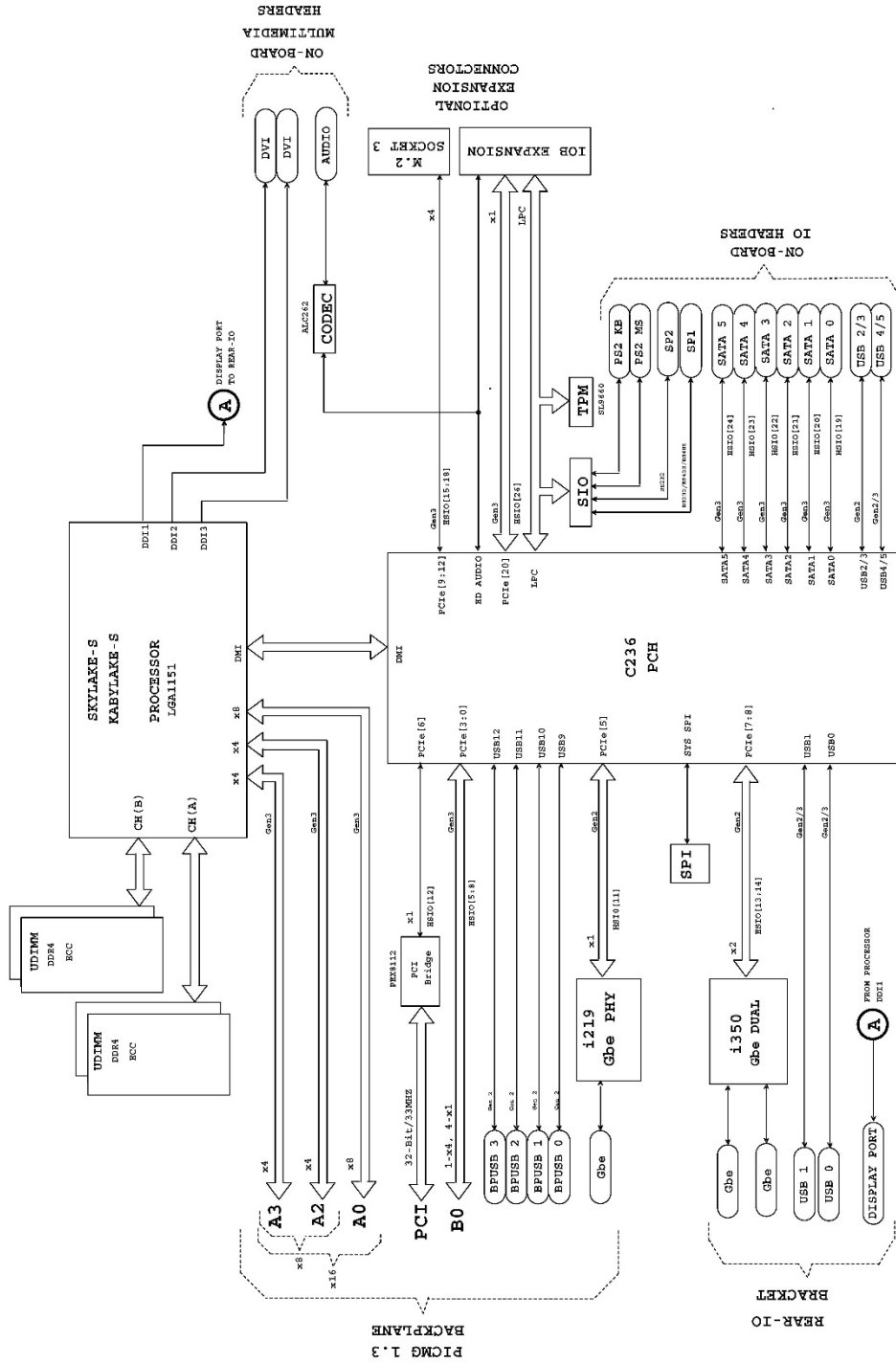
FCC

CE

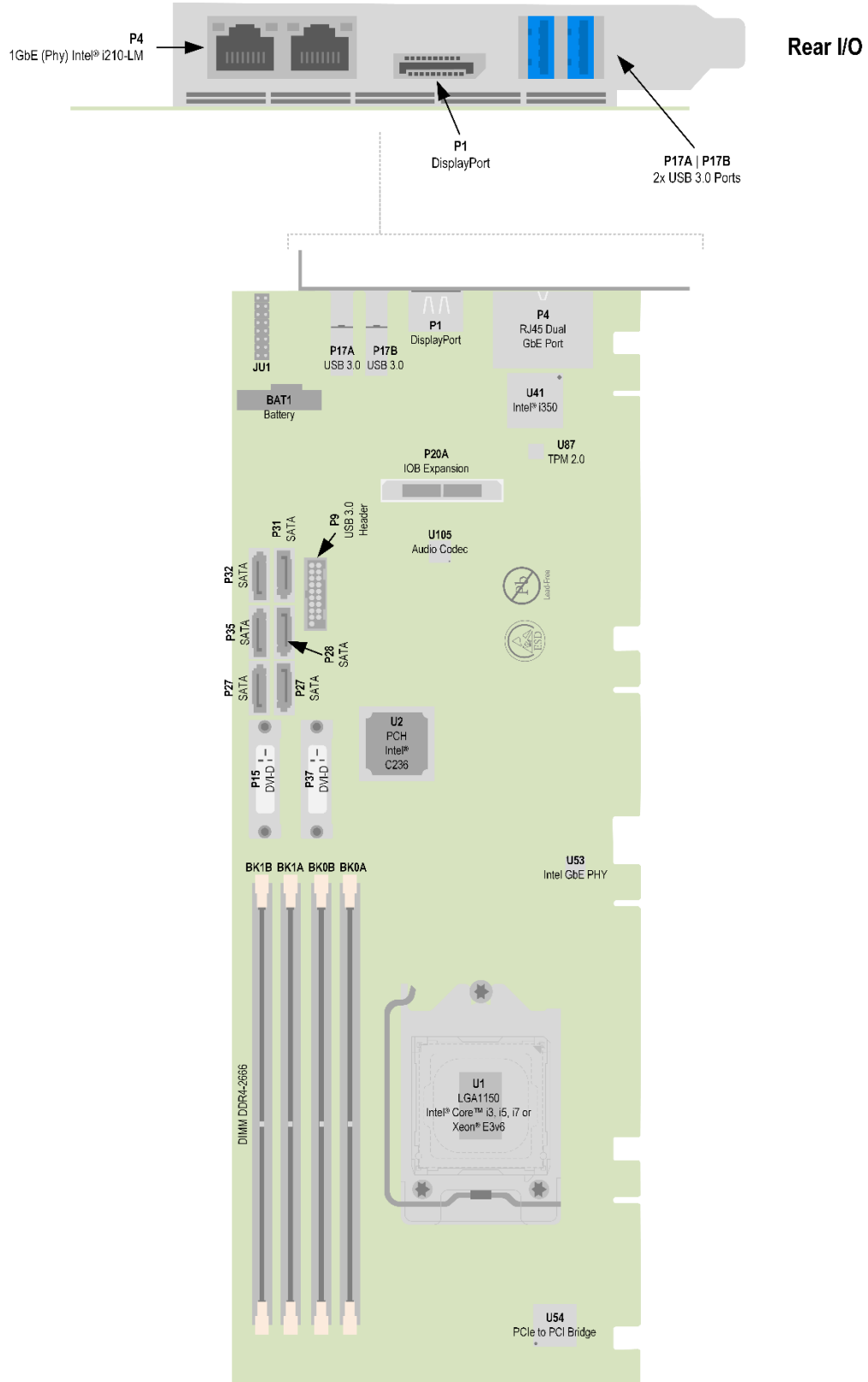
\*Numbers noted are dependent on CPU selection. Please [contact Trenton Systems](#) for specific CPU environmental specs.



# BLOCK DIAGRAM



# LAYOUT DRAWING





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